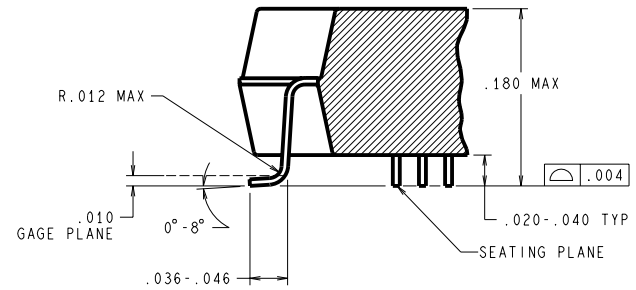
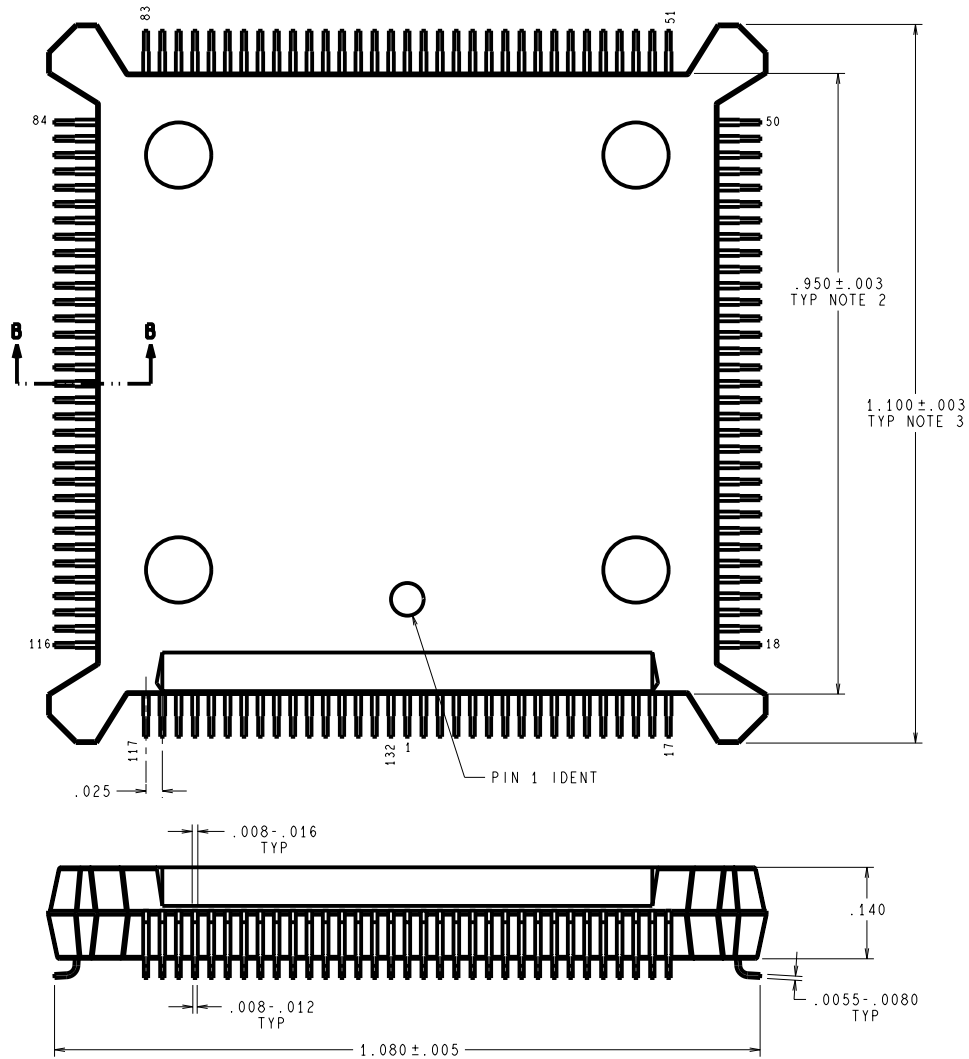


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW ALL IN INCH DIMS.	11102	09/01/95	DEG



SECTION B-B
SCALE: 12X

NOTES: UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES

- STANDARD LEAD FINISH:
300 MICROINCHES MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION .010in PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION .006in PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-069, VARIATION AE,
DATED OCT/90.

APPROVALS		DATE	National Semiconductor		
DRAWN	<i>D. E. Grady</i>	09/01/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.			PLASTIC QUAD FLATPACK, 132 LEAD		
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VF132A	E
INCH (MM)		DO NOT SCALE DRAWING		SHEET 1 of 1	